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RG12864B-BIW-V

SPECIFICATION

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

Release DATE:



Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2008/01/23		First issue
A	2012/09/06		Add Recommendable
			storage
			Modify General
			Specification
В	2014/07/17		Correct Contour
			Drawing
			Remove IC
			information
С	2016/02/25		Modify Precautions in
			use of LCD Modules
			& Static electricity
			test
D	2017/04/26		Modify Backlight
			Information



Contents

- 1. General Specification
- 2. Module Classification Information
- 3.Interface Pin Function
- 4. Contour Drawing & Block Diagram
- 5. Optical Characteristics
- 6. Absolute Maximum Ratings
- 7. Electrical Characteristics
- 8.Backlight Information
- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of LCD Modules
- 12. Material List of Components for RoHs
- 13. Recommendable Storage



1.General Specification

The Features is described as follow:

■ Module dimension: 75.0 x 52.7 x 8.9 (max.) mm

■ View area: 58.8 x 31.4mm

Active area: 55.01 x 27.49 mm

■ Number of dots: 128 x 64

■ Dot size: 0.40 x 0.40 mm

■ Dot pitch: 0.43 x 0.43 mm

■ LCD type: STN Negative, Blue Transmissive

■ Duty: 1/64

■ View direction: 6 o'clock

■ Backlight Type: LED White

■ IC:NT7107, NT7108



2. Module Classification Information

<u>R</u>	<u>G</u>	<u>12864</u>	<u>B</u>	_	<u>B</u>	<u>I</u>	W	_	<u>V</u>
()	2	3	4		(5)	6	7	_	8

Item	Description							
1	R : Raystar O	R : Raystar Optronics Inc.						
2	Dioploy	C: Character Type,		T:TAB Type				
2	Display	G: Graphic Type		X:COG Type				
3	Display Font :	128 * 64 dot						
4	Serials code:							
		P→TN Positive, Gray		V→FSTN No	egative, Blue			
		N→TN Negative,		T→FSTN Ne	egative, Black			
		L→VA Negative		D→FSTN N	egative (Double film)			
		H→ HTN Positive, Gray		F→FSTN Po	ositive			
5	LCD	I→HTN Negative, Black		K→FSC Neg	gative			
		U→HTN Negative, Blue		S→FSC Pos	sitive			
		B→STN Negative, Blue		E→ISTN Ne	gative, Black			
		G→STN Positive, Gray		C→CSTN N	egative, Black			
		Y→STN Positive, Yellow		A→ASTN Negative, Black				
		A: Reflective, N.T, 6:00		K: Transflective, W.T,12:00				
	Polarizer Type,	D: Reflective, N.T, 12:00		1 : Transflective, U.T,6:00				
		G: Reflective, W. T, 6:00		4: Transflective, U.T.12:00				
	Temperature	J: Reflective, W. T, 12:00			ssive, N.T,6:00			
6	range,	0: Reflective, U. T, 6:00		F: Transmissive, N.T,12:00				
	90,	3: Reflective, U. T, 12:0		I: Transmissive, W. T, 6:00				
	View	B: Transflective, N.T,6:0	00		ssive, W.T,12:00			
	direction	E: Transflective, N.T.12		2: Transmissive, U. T, 6:00				
		H: Transflective, W.T,6:			ssive, U.T,12:00			
	1	N→ Without backlight		D, White	H→LED, High light White			
		P→EL, Blue), Amber	S→LED, Full color			
		T→EL, Green	R→LED	•	J→DIP LED, Blue			
7	Backlight	D→EL, White), Orange	K→DIP LED, White			
		M→EL, Yellow Green	B→LED	<i>'</i>	E→DIP LED, Yellow			
		F→CCFL, White		, Dual color	L→DIP LED, Amber			
		Y→LED, Yellow Green	C→LED), Full color	I→DIP LED, Red			
	7	G→LED, Green						
8	Special code	V: Build in Negative Volta	age					

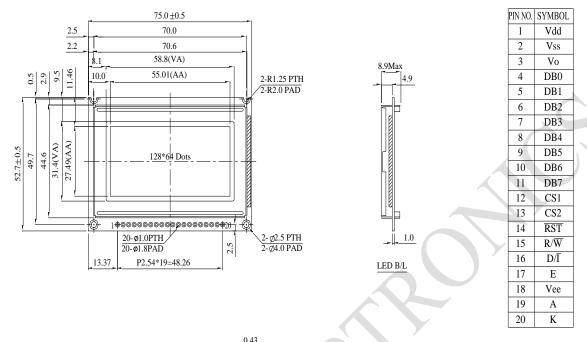


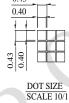
3.Interface Pin Function

Pin No.	Symbol	Level	Description
1	VDD	5.0V	Supply voltage for logic
2	Vss	0V	Ground
3	Vo	(Variable)	Contrast Adjustment
4	DB0	H/L	Data bus line
5	DB1	H/L	Data bus line
6	DB2	H/L	Data bus line
7	DB3	H/L	Data bus line
8	DB4	H/L	Data bus line
9	DB5	H/L	Data bus line
10	DB6	H/L	Data bus line
11	DB7	H/L	Data bus line
12	CS1	L	Select Column 1~ Column 64
13	CS2	L	Select Column 65~ Column 128
14	/RST	L	Reset signal
15	R/W	H/L	H: Read (Module> MPU) L: Write(MPU> Module)
16	D/I	H/L	H: Data, L: Instruction
17	E	Н	Énable signal
18	Vee		Negative Voltage output
19	Α		Power Supply for LED backlight (+)
20	K	_	Power Supply for LED backlight (-)

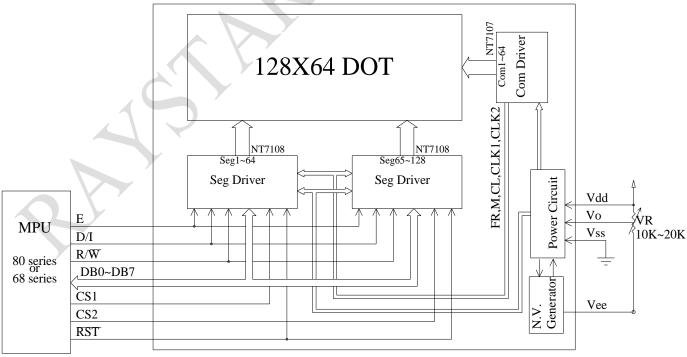


4. Contour Drawing & Block Diagram





The non-specified tolerance of dimension is ± 0.3 mm.



External contrast adjustment.

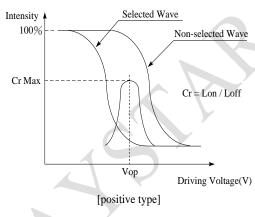


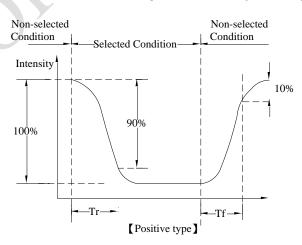
5.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR <u>≥</u> 2	0	_	20	ψ= 180°
View Angle	θ	CR <u>≥</u> 2	0	_	40	ψ= 0°
	θ	CR <u>≥</u> 2	0	_	30	ψ= 90°
	θ	CR <u>≥</u> 2	0	1	30	ψ= 270°
Contrast Ratio	CR	_		3	_	_
Poononce Time	T rise	- /	1	200	300	ms
Response Time	T fall		7	250	350	ms

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)





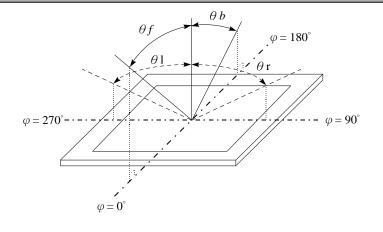
Conditions:

Operating Voltage : Vop Viewing Angle(θ , ϕ) : 0° , 0°

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle(CR≥2)







6.Absolute Maximum Ratings

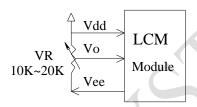
Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	Ç
Storage Temperature	T _{ST}	-30	_	+80	°C
Supply Voltage For Logic	V _{DD} -Vss	-0.3	_	7.0	V
Driver Supply Voltage	V _{LCD}	V _{EE} -0.3		V _{DD} +0.3	V



7. Electrical Characteristics

ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Supply Voltage For	V _{DD} -V _{SS}	_	4.5	5.0	5.5	\ \
Logic	ע סט- ע 35		4.5	5.0	5.5	V
		Ta=-20°C				Ĵ
Supply Voltage For			_	_	9.6	V
LCD	V_{DD} - V_{O}	Ta=25°C	7.8	8.0	8.2	V
*Note		Ta=70°C	7.6		-	V
Input High Volt.	VIH	_	0.7 V _{DD}		V _{DD}	V
Input Low Volt.	VIL	-	0	_	0.8	V
Output High Volt.	Voh	- <	2.4	_	_	V
Output Low Volt.	Vol		> -	_	0.4	V
Supply Current	I_{DD}	V _{DD} =5.0V	3.0	4.0	5.0	mA

^{*} Note: Please design the VOP adjustment circuit on customer's main board





8.Backlight Information

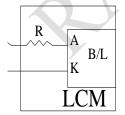
Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	_	48	60	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	٧	- ()~
Reverse Voltage	VR	_	_	5	٧	-
Luminance	IV	520	650	_	cd/m²	ILED=48mA
(Without LCD)		020	000		ou/iii	TELS TOTAL
LED Life Time					X	IĽED=48mA
(For Reference	_	_	50K		Hr.	25℃,50-60%RH,
only)				X		(Note 1)
Color	White) ′		

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.

.Drive from pin19,pin20





9. Reliability

	Environmental Test									
Test Item	Content of Test	Test Condition	Note							
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2							
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2							
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs								
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1							
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2							
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles								
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3							
Static electricity test	Endurance test applying the electric stress to the terminal.	VS= ± 600 V(contact), ± 800 v(air), RS= 330Ω CS= 150 pF 10 times								

Content of Reliability Test (Wide temperature, -20°C~70°C)

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



10.Inspection specification

NO	Item	Criterion								
		1.1 Missing vert	1.1 Missing vertical, horizontal segment, segment contrast							
		defect.								
		1.2 Missing char	racter, do	t or icon.						
	Electrical	1.3 Display malf	unction.							
01	Testing	1.4 No function	or no displ	ay.		0.65				
	resung	1.5 Current cons	sumption e	exceeds product sp	pecifications.					
		1.6 LCD viewing	angle def	fect.						
		1.7 Mixed produ	ct types.							
		1.8 Contrast def	ect.							
	Black or white	2.1 White and b	lack spots	on display \leq 0.25	mm, no more than					
02	spots on LCD	three white o	r black sp	ots present.	Y	2.5				
02	(display only)	2.2 Densely spaced: No more than two spots or lines within								
	(diopidy offiy)	3mm								
		3.1 Round type		ring drawing						
		Φ=(x + y) /	2	SIZE	Acceptable Q TY					
				Ф≦0.10	Accept no dense					
				0.10<Φ≦0.20	2					
				0.20<Φ≦0.25	1	2.5				
		1 2		0.25<Ф	0	2.0				
	LCD black	x	4							
	spots, white	→	<u> </u>							
03	spots,	• .	x Y							
	contamination		T							
	(non-display)	3.2 Line type : (/	As followin	g drawing)						
			Length	Width	Acceptable Q TY					
1	Y	_ / X w		W≦0.02	Accept no dense					
		→ ; H—	L≦3.0	0.02 < W \u2229 0.03		2.5				
		*	L≦2.5	0.03 <w \u220e90.05<="" td=""><td>2</td><td></td></w>	2					
				0.05 < W	As round type					





04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	Size Φ $Φ \le 0.20$ $0.20 < Φ \le 0.50$	Acceptable Q TY Accept no dense	2.5
	to find, must check in		0.50<Φ≦1.00 1.00<Φ	0	
		Total Q TY	3		



NO	Item	Criterion			AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination			
			Glass thickness a: LCD	hickness Side length	
		6.1 General glass chip 6.1.1 Chip on panel sur	: face and crack between	panels:	
		z: Chip thickness	y: Chip width	x: Chip length	
06	Chipped	Z≦1/2t	Not over viewing area	x≦1/8a	2.5
	glass	1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a	
	⊙ If there are 2 or more chips, x is total length of each chip.6.1.2 Corner crack:				
		z: Chip thickness	y: Chip width	x: Chip length	
8		Z≦1/2t	Not over viewing area	x≦1/8a	
	7	1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a	
⊙ If there are 2 or more chips, x is the			chips, x is the total leng	th of each chip.	



NO	Item	Criterion	AQL		
		Symbols:			
		x: Chip length y: Chip width z: Chip thickness			
		k: Seal width t: Glass thickness a: LCD side length			
		L: Electrode pad length			
		6.2 Protrusion over terminal :			
		6.2.1 Chip on electrode pad :			
		Z			
		AX.			
		y: Chip width x: Chip length z: Chip thickness			
		$y \le 0.5 \text{mm} \qquad \qquad x \le 1/8 \text{a} \qquad \qquad 0 < z \le t$			
		6.2.2 Non-conductive portion:			
		S.Z.Z IVON CONGRESSIVE PORTION.			
06	Glass		2.5		
	crack		2.0		
		y			
		X, X			
		y: Chip width x: Chip length z: Chip thickness			
		$y \le L$ $x \le 1/8a$ $0 < z \le t$			
		⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO			
		must remain and be inspected according to electrode terminal			
		specifications.			
		⊙ If the product will be heat sealed by the customer, the alignment			
		mark not be damaged.			
		6.2.3 Substrate protuberance and internal crack.			
		X			
		$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			
		y = 1/3L			



NO	Item	Criterion	AQL	
07	Cracked glass	The LCD with extensive crack is not acceptable.		
		8.1 Illumination source flickers when lit.	0.65	
08	Backlight elements 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards.			
		8.3 Backlight doesn't light or color wrong.	0.65	
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.	2.5 0.65	
		9.2 Bezel must comply with job specifications.	0.00	
		10.1 COB seal may not have pinholes larger than 0.2mm or contamination.10.2 COB seal surface may not have pinholes through to the	2.5	
		IC.	2.5	
		 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 		
10	PCB · COB	10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.	0.65	
	10.7 The jumper on the PCB should conform to the product characteristic chart.		0.65	
	4	10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5	
		10.9 The Scraping testing standard for Copper Coating of PCB	2.5	
Y		X * Y<=2mm2		
7		11.1 No un-melted solder paste may be present on the PCB.	2.5	
		11.2 No cold solder joints, missing solder connections,	2.5	
11	Soldering	oxidation or icicle.		
		11.3 No residue or solder balls on PCB.	2.5	
		11.4 No short circuits in components on PCB.	0.65	





NO	Item	Criterion	AQL
140	пеш	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 	2.5 0.65 2.5 2.5
12	General appearance	 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. 12.12 Visual defect outside of VA is not considered to be rejection. 	2.5 2.5 2.5 0.65 0.65 0.65



11.Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) Raystar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.



12. Material List of Components for RoHs

1. RAYSTAR Optronics. Inc. hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

- 2.Process for RoHS requirement: (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.



13. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.



Page: 1

		raye. i			
	LCM Sample	Estimate Feedback Sheet			
Module Number :					
1 · Panel Specification :					
1. Panel Type:	□ Pass	□ NG ,			
2. View Direction:	□ Pass	□ NG ,			
3. Numbers of Dots:	□ Pass	□ NG ,			
4. View Area:	□ Pass	□ NG ,			
5. Active Area:	□ Pass	□ NG ,			
6.Operating Temperature:	□ Pass	□ NG ,			
7.Storage Temperature:	□ Pass	□ NG ,			
8.Others:	•				
2 · Mechanical Specification :					
1. PCB Size:	□ Pass	□ NG ,			
2.Frame Size :	□ Pass	□ NG ,			
3.Materal of Frame:	□ Pass	□ NG ,			
4.Connector Position:	□ Pass	□ NG ,			
5.Fix Hole Position:	□ Pass	□ NG ,			
6.Backlight Position:	□ Pass	□ NG ,			
7. Thickness of PCB:	□ Pass	□ NG ,			
8. Height of Frame to PCB:	□ Pass	□ NG ,			
9.Height of Module:	□ Pass	□ NG ,			
10.Others:	□ Pass	□ NG ,			
3 · Relative Hole Size :					
1.Pitch of Connector:	□ Pass	□ NG ,			
2.Hole size of Connector:	□ Pass	□ NG ,			
3.Mounting Hole size:	□ Pass	□ NG ,			
4.Mounting Hole Type:	□ Pass	□ NG ,			
5.Others:	□ Pass	□ NG ,			
4 · Backlight Specification :					
1.B/L Type:	□ Pass	□ NG ,			
2.B/L Color:	□ Pass	□ NG ,			
3.B/L Driving Voltage (Reference for LED Type) : □ Pass □ NG ,					
4.B/L Driving Current:	□ Pass	□ NG ,			
5.Brightness of B/L:	□ Pass	□ NG ,			
6.B/L Solder Method:	□ Pass	□ NG ,			
7.Others:	□ Pass	□ NG ,			

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Module Number:					
5 · Electronic Characteristics of Module :					
1.Input Voltage:	□ Pass	□ NG ,			
2.Supply Current:	□ Pass	□ NG ,			
3.Driving Voltage for LCD:	□ Pass	□ NG ,			
4.Contrast for LCD:	□ Pass	□ NG ,			
5.B/L Driving Method:	□ Pass	□ NG ,			
6.Negative Voltage Output:	□ Pass	□ NG ,			
7.Interface Function:	□ Pass	□ NG ,			
8.LCD Uniformity:	□ Pass	□ NG ,			
9.ESD test:	□ Pass	□ NG ,			
10.Others:	□ Pass	□ NG ,			
Customer Signature:		Date: / /			